



SGM8278-2

Low Noise, High Voltage, Rail-to-Rail I/O Operational Amplifier

GENERAL DESCRIPTION

The SGM8278-2 is a dual, low noise, precision, high voltage operational amplifier, which can operate from 3V to 36V single supply or from $\pm 1.5\text{V}$ to $\pm 18\text{V}$ dual power supplies. It provides rail-to-rail input with a wide input common mode voltage range and rail-to-rail output voltage swing.

The SGM8278-2 provides high slew rate, low noise, low offset, drift and bias current.

The SGM8278-2 is available in Green SOIC-8, MSOP-8, TDFN-2 $\times$ 2-8AL, TDFN-3 $\times$ 3-8BL and WLCSP-1.57 $\times$ 1.57-8B packages. It is specified over the extended -40°C to $+125^{\circ}\text{C}$ temperature range.

FEATURES

- Rail-to-Rail Input and Output
- Support Single or Dual Power Supplies
- Wide Input Common Mode and Differential Voltage Ranges
- Low Input Offset Voltage: 2mV (MAX)
- Low Input Bias Current
- Low Input Offset Current
- High Input Impedance
- High Output Current: 95mA (Able to Drive 32 Ω Load)
- Output Short-Circuit Protection
- Low Noise: 15nV/ $\sqrt{\text{Hz}}$ at 1kHz
- Gain-Bandwidth Product: 3.3MHz
- Slew Rate: 2V/ μs
- -40°C to $+125^{\circ}\text{C}$ Operating Temperature Range
- Available in Green SOIC-8, MSOP-8, TDFN-2 $\times$ 2-8AL, TDFN-3 $\times$ 3-8BL and WLCSP-1.57 $\times$ 1.57-8B Packages

APPLICATIONS

High Impedance Sensor
Photodiode Amplifier
High End, Professional Audio
DAC Output Amplifier
Medical

PACKAGE/ORDERING INFORMATION

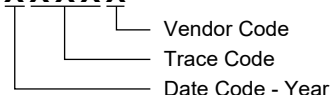
MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM8278-2	SOIC-8	-40°C to +125°C	SGM8278-2XS8G/TR	SGM 82782XS8 XXXXX	Tape and Reel, 4000
	MSOP-8	-40°C to +125°C	SGM8278-2XMS8G/TR	SGM82782 XMS8 XXXXX	Tape and Reel, 4000
	TDFN-2×2-8AL	-40°C to +125°C	SGM8278-2XTDE8G/TR	R41 XXXX	Tape and Reel, 3000
	TDFN-3×3-8BL	-40°C to +125°C	SGM8278-2XTDD8G/TR	SGM R42DD XXXXX	Tape and Reel, 4000
	WLCSP-1.57×1.57-8B	-40°C to +125°C	SGM8278-2XG/TR	XXXX R40	Tape and Reel, 3000

MARKING INFORMATION

NOTE: XXXX = Date Code and Trace Code. XXXXX = Date Code, Trace Code and Vendor Code.

SOIC-8/MSOP-8

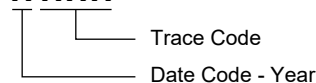
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TDFN-2×2-8AL

YYY — Serial Number

X XXX

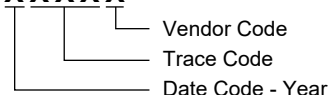


TDFN-3×3-8BL

Serial Number

YYYDD

XXXXX



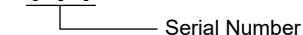
WLCSP-1.57×1.57-8B

Date Code - Year

Trace Code

XXXX

YYY



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $+V_S$ to $-V_S$	40V
Input/Output Voltage Range.....	$(-V_S) - 0.3V$ to $(+V_S) + 0.3V$
Junction Temperature	+150°C
Storage Temperature Range.....	-65°C to +150°C
Lead Temperature (Soldering, 10s)	+260°C
ESD Susceptibility	
HBM.....	4000V
CDM	1000V

RECOMMENDED OPERATING CONDITIONS

Operating Temperature Range	-40°C to +125°C
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NOTE: 1. It is recommended that CMOS device adopts the proper power supply sequence. Always sort the V_S first, followed by the inputs and outputs.

OVERSTRESS CAUTION

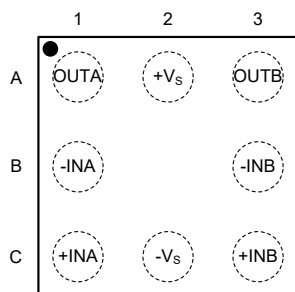
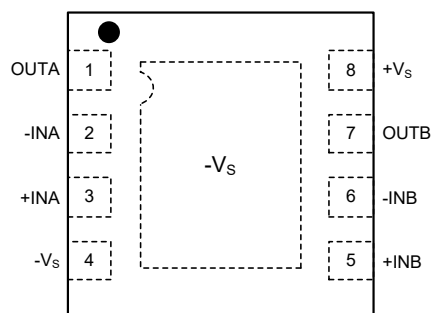
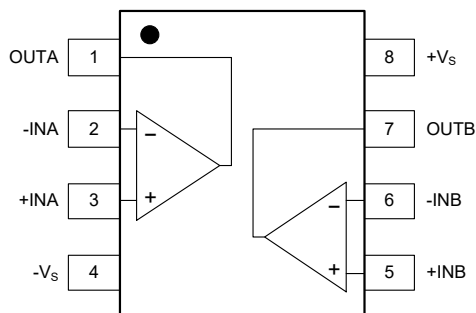
Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATIONS**(TOP VIEW)****WLCSP-1.57x1.57-8B****(TOP VIEW)****TDFN-2x2-8AL/TDFN-3x3-8BL****(TOP VIEW)****SOIC-8/MSOP-8**

NOTE: For TDFN-2x2-8AL and TDFN-3x3-8BL packages, exposed pad can be connected to $-V_S$ or left floating.

ELECTRICAL CHARACTERISTICS

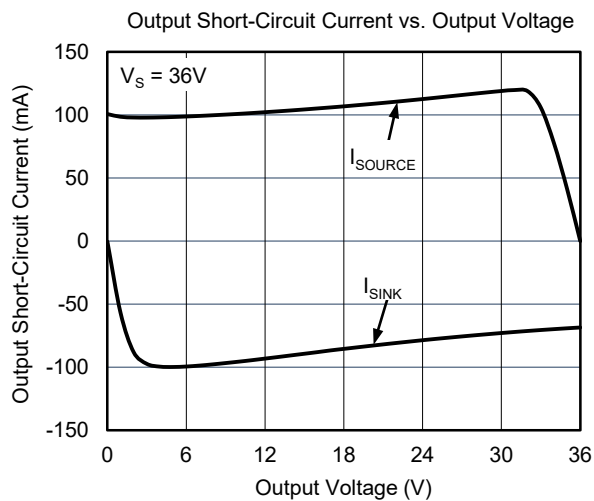
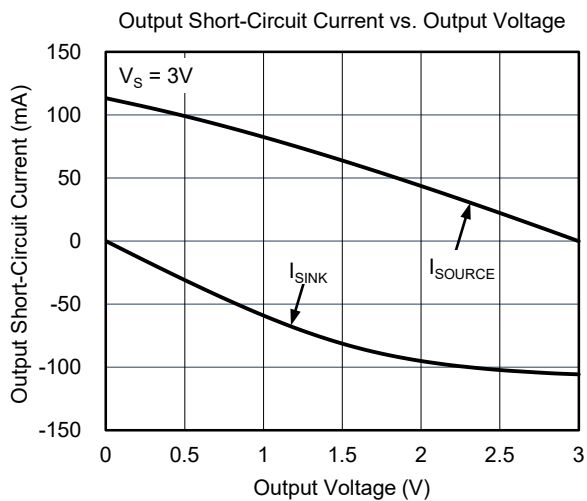
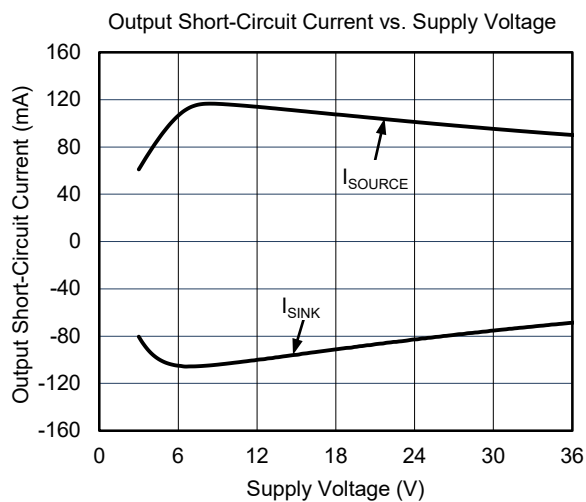
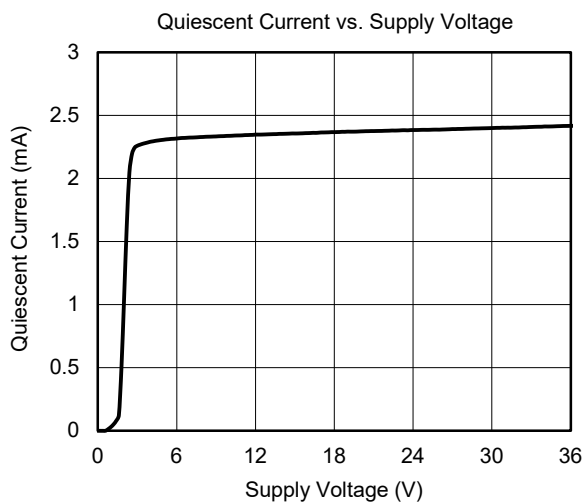
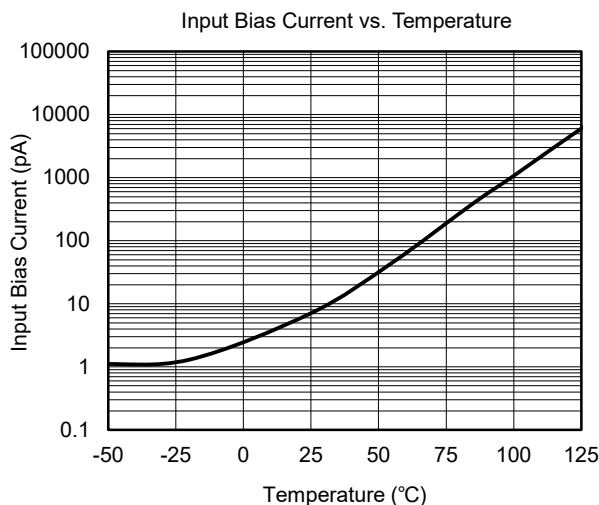
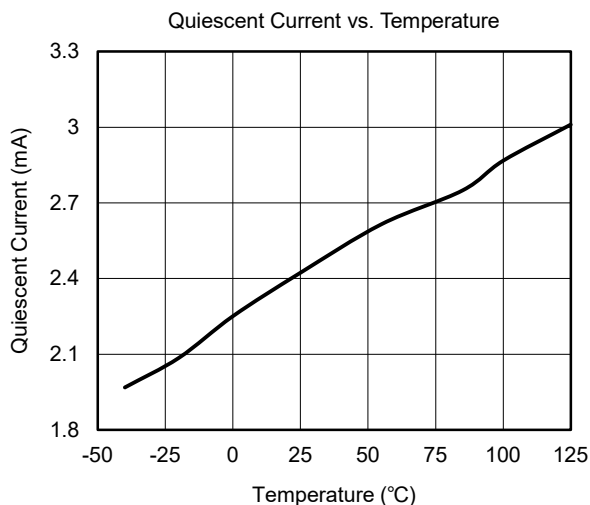
(At $T_A = +25^\circ\text{C}$, $V_S = \pm 1.5\text{V}$ to $\pm 18\text{V}$ and $R_L = 2\text{k}\Omega$ connected to 0V , Full = -40°C to $+125^\circ\text{C}$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
Input Characteristics							
Input Offset Voltage	V _{OS}	V _{CM} = 0V	+25°C		0.4	2	mV
			Full			2.5	
Input Offset Voltage Drift	ΔV _{OS} /ΔT		Full		2		μV/°C
Input Bias Current	I _B	V _{CM} = 0V	+25°C		±10	800	pA
Input Offset Current	I _{OS}	V _{CM} = 0V	+25°C		±10	800	pA
Maximum Differential Input Voltage	I _{VID}		Full			(+V _S) - (-V _S)	V
Maximum Input Difference Bias Current	I _{IID}	V _S = ±18V, V _{ID} = ±18V	+25°C		2	3.5	μA
			Full			5	
Input Common Mode Voltage Range	V _{CM}		Full	(-V _S) - 0.1		(+V _S) + 0.1	V
Common Mode Rejection Ratio	CMRR	V _S = ±18V, (-V _S) - 0.1V < V _{CM} < (+V _S) - 2V	+25°C	98	115		dB
			Full	95			
		V _S = ±18V, (-V _S) - 0.1V < V _{CM} < (+V _S) + 0.1V	+25°C	83	100		
			Full	80			
Open-Loop Voltage Gain	A _{OL}	(-V _S) + 0.2V < V _{OUT} < (+V _S) - 0.2V, R _L = 10kΩ	+25°C	103	125		dB
			Full	100			
		(-V _S) + 0.5V < V _{OUT} < (+V _S) - 0.5V, R _L = 2kΩ	+25°C	100	120		
			Full	97			
Output Characteristics							
Output Voltage Swing from Rail	V _{OUT}	V _S = ±18V, R _L = 10kΩ	+25°C		25	40	mV
			Full			60	
		V _S = ±18V, R _L = 2kΩ	+25°C		120	150	
			Full			230	
		V _S = ±3V, R _L = 600Ω	+25°C		65	85	
			Full			125	
		V _S = ±3V, R _L = 32Ω	+25°C		920	1200	
			Full			1500	
Output Short-Circuit Current	I _{SC}	V _S = ±3V	+25°C	55	95		mA
Power Supply							
Operating Voltage Range	V _S		Full	3		36	V
Quiescent Current	I _Q	I _{OUT} = 0A	+25°C		2.4	3.2	mA
			Full			4	
Power Supply Rejection Ratio	PSRR	V _S = 5V to 36V	+25°C	100	124		dB
			Full	97			

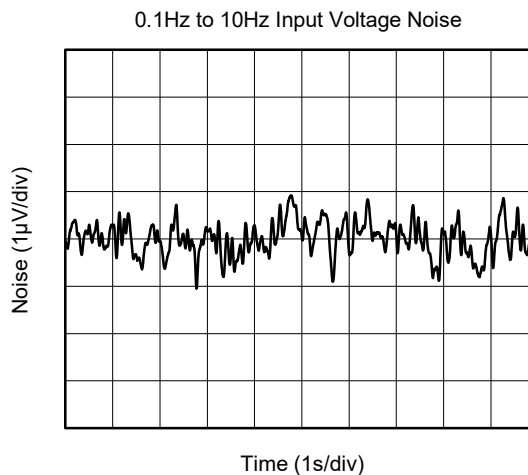
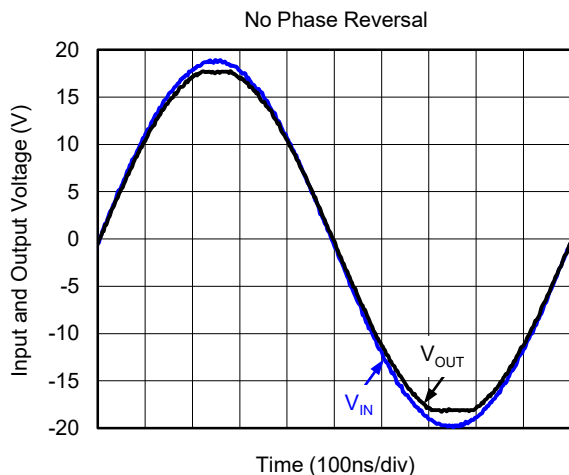
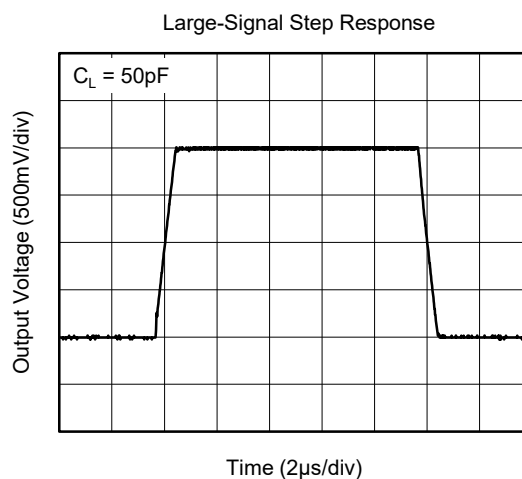
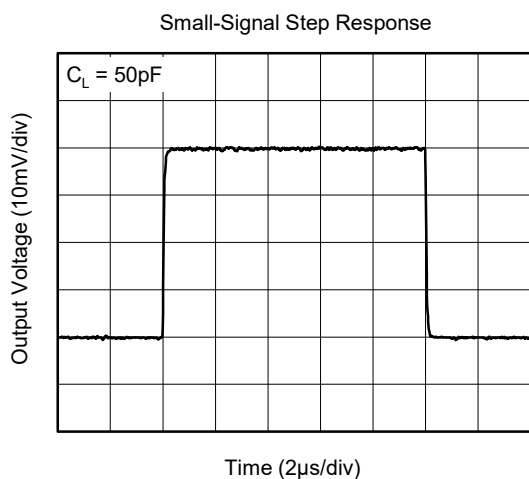
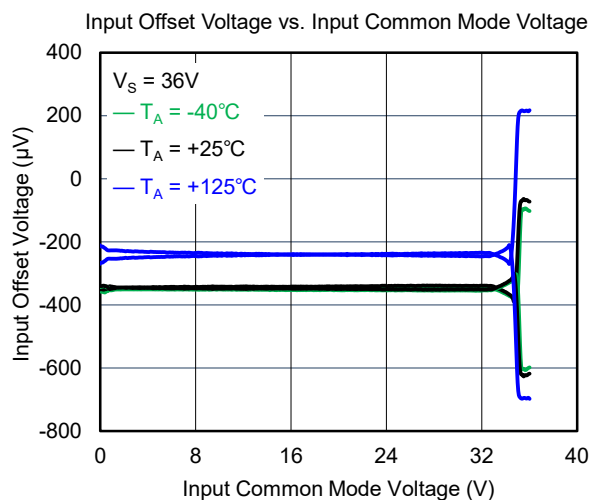
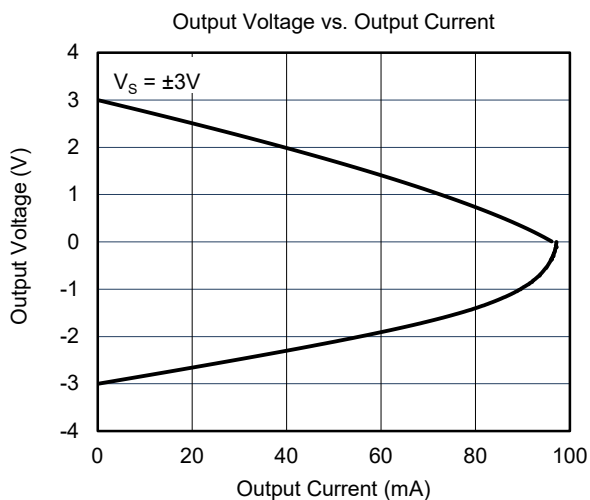
ELECTRICAL CHARACTERISTICS (continued)(At $T_A = +25^\circ\text{C}$, $V_S = \pm 1.5\text{V}$ to $\pm 18\text{V}$ and $R_L = 2\text{k}\Omega$ connected to 0V , Full = -40°C to $+125^\circ\text{C}$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
Dynamic Performance							
Gain-Bandwidth Product	GBP	C _L = 50pF	+25°C		3.3		MHz
Phase Margin	φ _O	C _L = 50pF	+25°C		70		°
Slew Rate	SR	G = +1	+25°C		2		V/μs
Overload Recovery Time	ORT	V _{IN} × G > V _S	+25°C		0.4		μs
Total Harmonic Distortion + Noise	THD+N	V _S = ±2.5V to ±18V, V _{OUT} = 2V _{P-P} , f = 1kHz, G = +1, R _L = 600Ω, BW = 20Hz to 80kHz	+25°C		0.001		%
		V _S = ±2.5V to ±18V, V _{OUT} = 2V _{P-P} , f = 1kHz, G = +1, R _L = 2kΩ, BW = 20Hz to 80kHz	+25°C		0.0005		
Noise							
Input Voltage Noise		f = 0.1Hz to 10Hz	+25°C		2		μV _{P-P}
Input Voltage Noise Density	e _n	f = 10Hz	+25°C		60		nV/√Hz
		f = 1kHz	+25°C		15		
Input Current Noise Density	i _n	f = 1kHz	+25°C		300		fA/√Hz

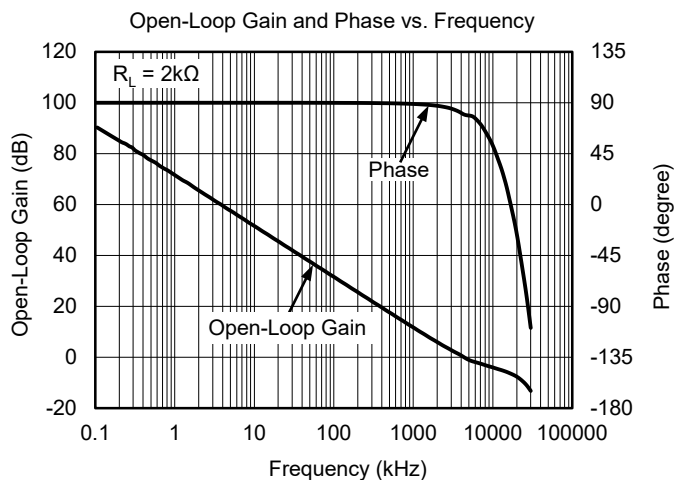
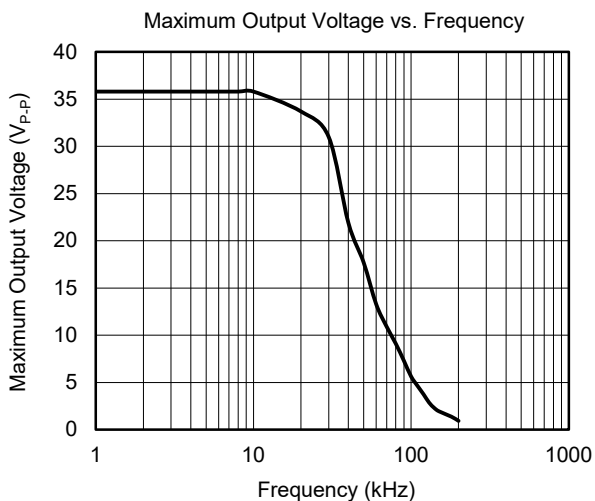
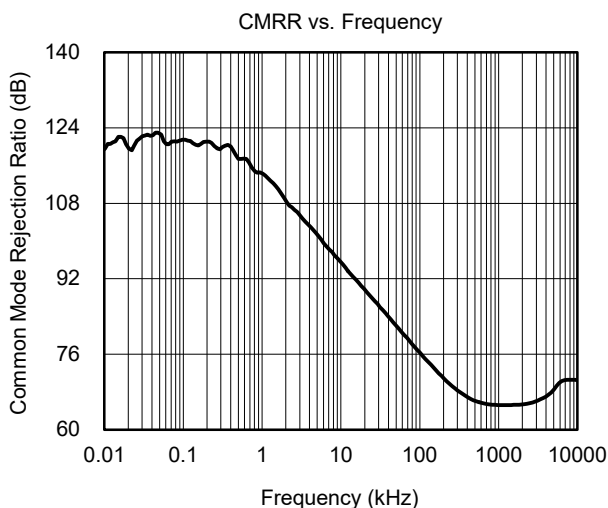
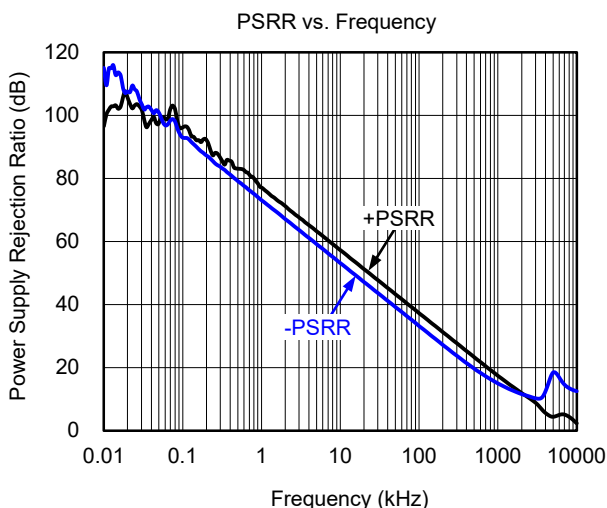
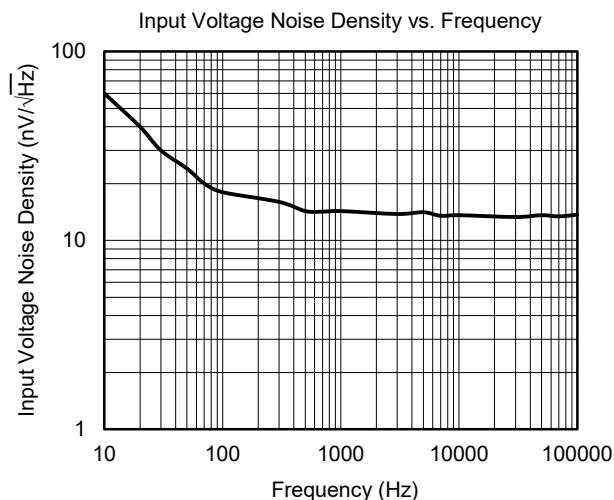
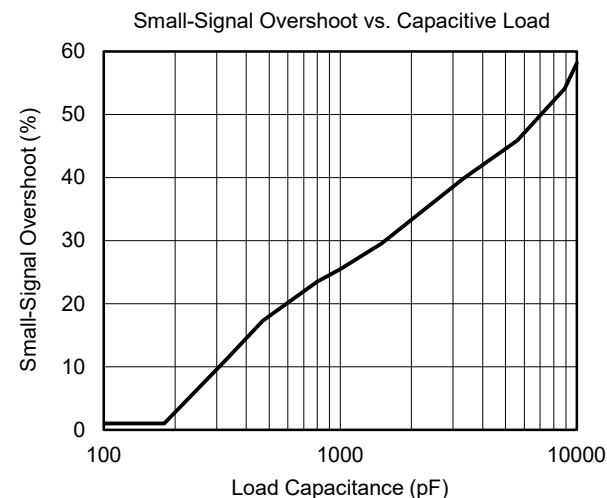
TYPICAL PERFORMANCE CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_S = \pm 18\text{V}$, unless otherwise noted.

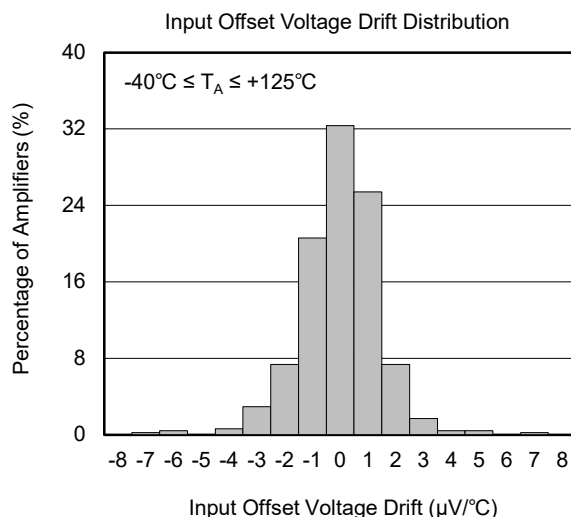
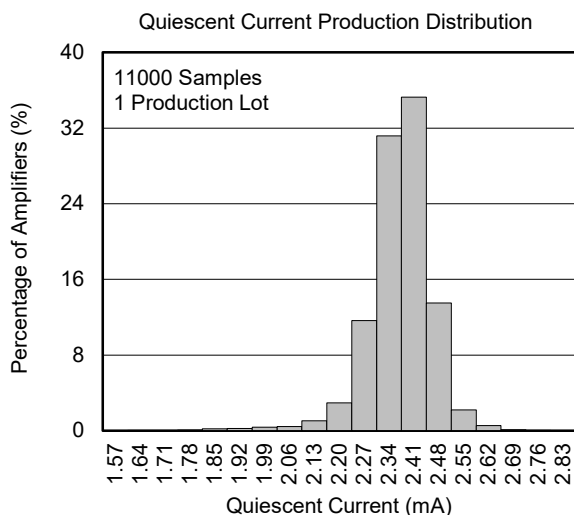
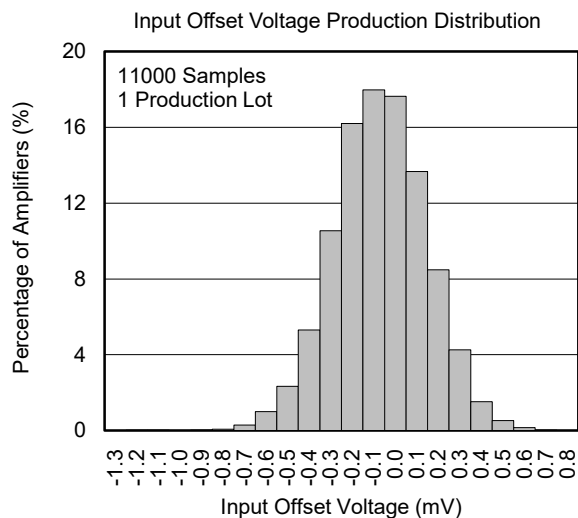
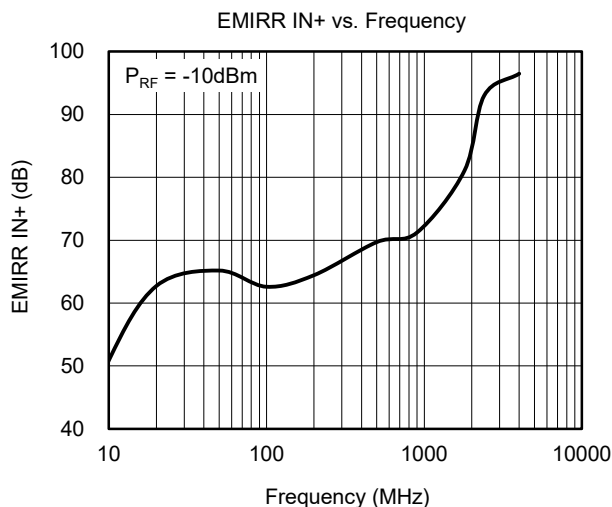
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

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TYPICAL PERFORMANCE CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 18\text{V}$, unless otherwise noted.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 18\text{V}$, unless otherwise noted.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

JULY 2022 – REV.A to REV.A.1

Page

Updated Typical Performance Characteristics section	8
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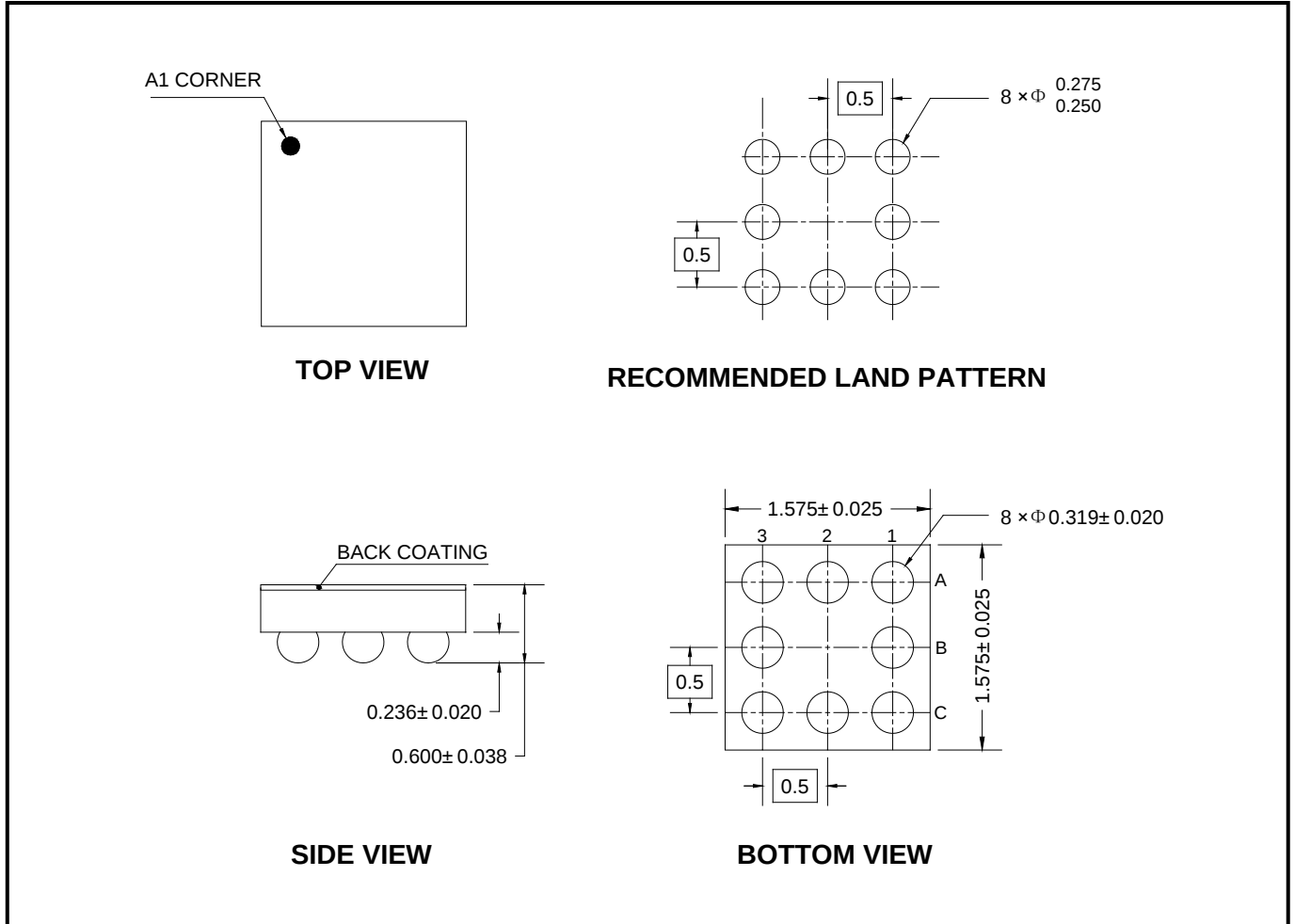
Changes from Original (DECEMBER 2020) to REV.A

Page

Changed from product preview to production data.....	All
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PACKAGE OUTLINE DIMENSIONS

WLCSP-1.57×1.57-8B

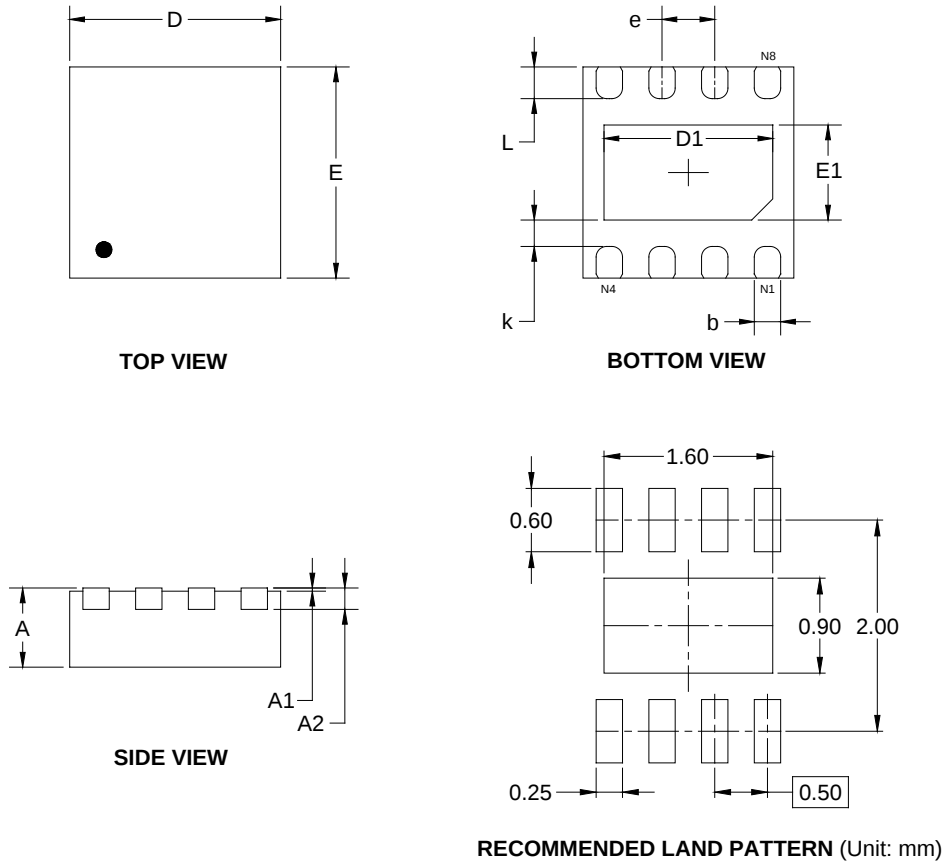


NOTES:

1. All linear dimensions are in millimeters.
2. This drawing is subject to change without notice.

PACKAGE OUTLINE DIMENSIONS

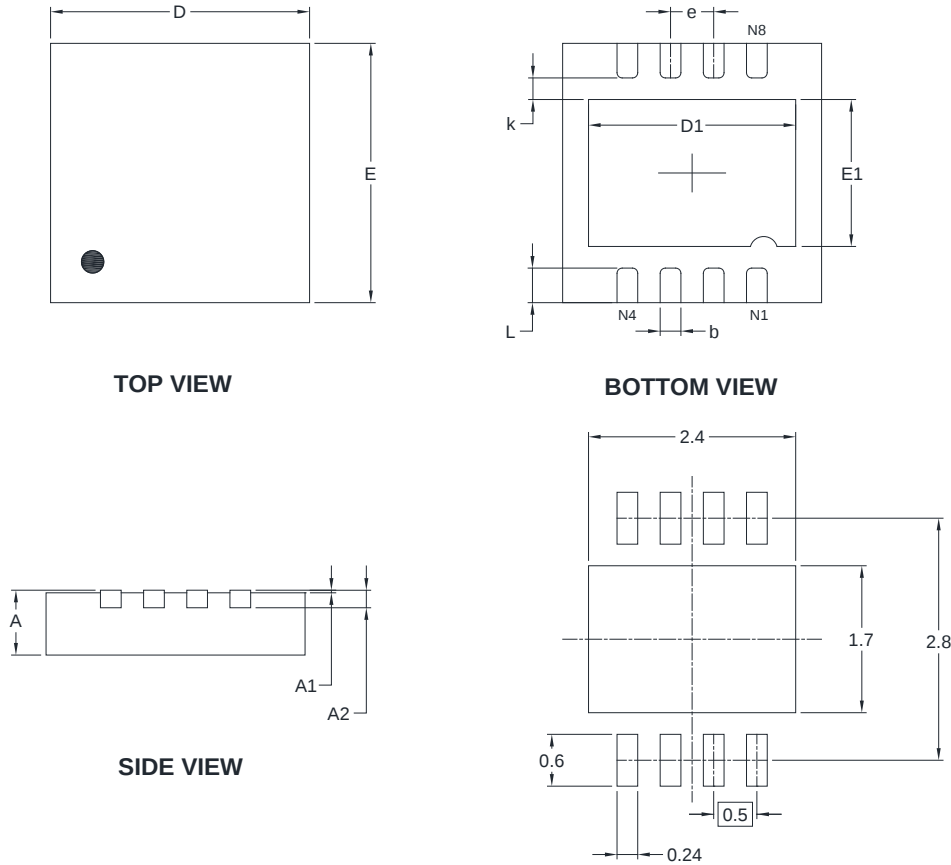
TDFN-2×2-8AL



Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.203 REF		
b	0.20	0.25	0.30
D	2 BSC		
D1	1.50	1.60	1.70
E	2 BSC		
E1	0.80	0.90	1.00
k	0.15	0.25	0.35
e	0.5 BSC		
L	0.25	0.30	0.35

PACKAGE OUTLINE DIMENSIONS

TDFN-3×3-8BL



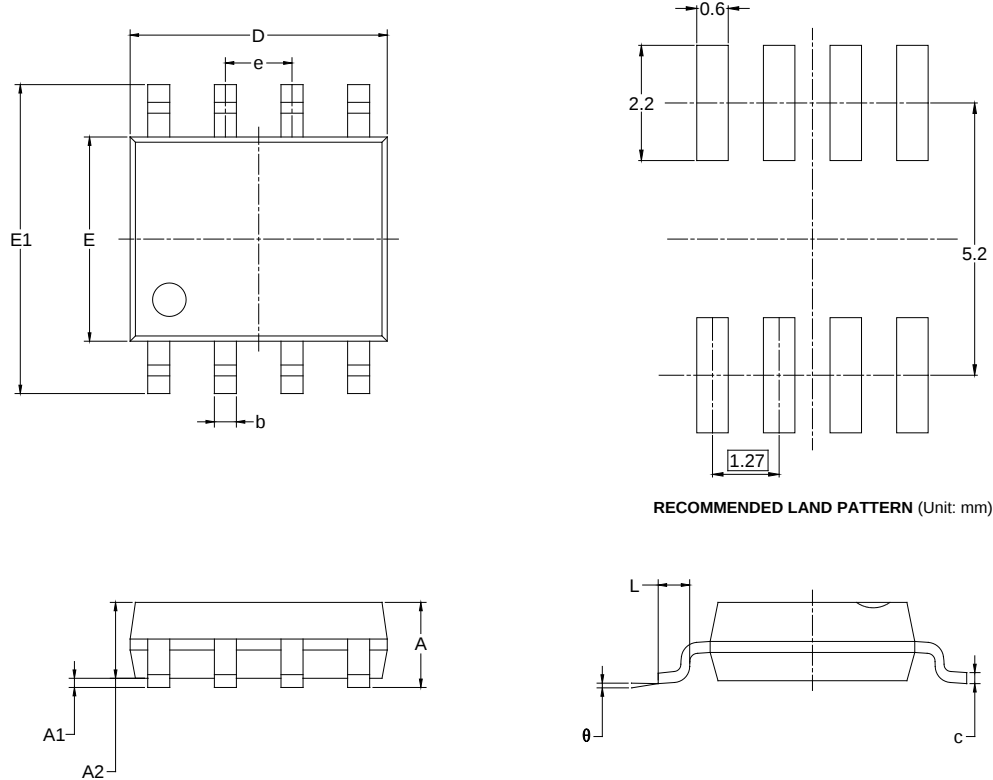
RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203 REF		0.008 REF	
D	2.900	3.100	0.114	0.122
D1	2.300	2.500	0.091	0.098
E	2.900	3.100	0.114	0.122
E1	1.600	1.800	0.063	0.071
k	0.200 MIN		0.008 MIN	
b	0.180	0.300	0.007	0.012
e	0.500 TYP		0.020 TYP	
L	0.300	0.500	0.012	0.020

NOTE: This drawing is subject to change without notice.

PACKAGE OUTLINE DIMENSIONS

SOIC-8



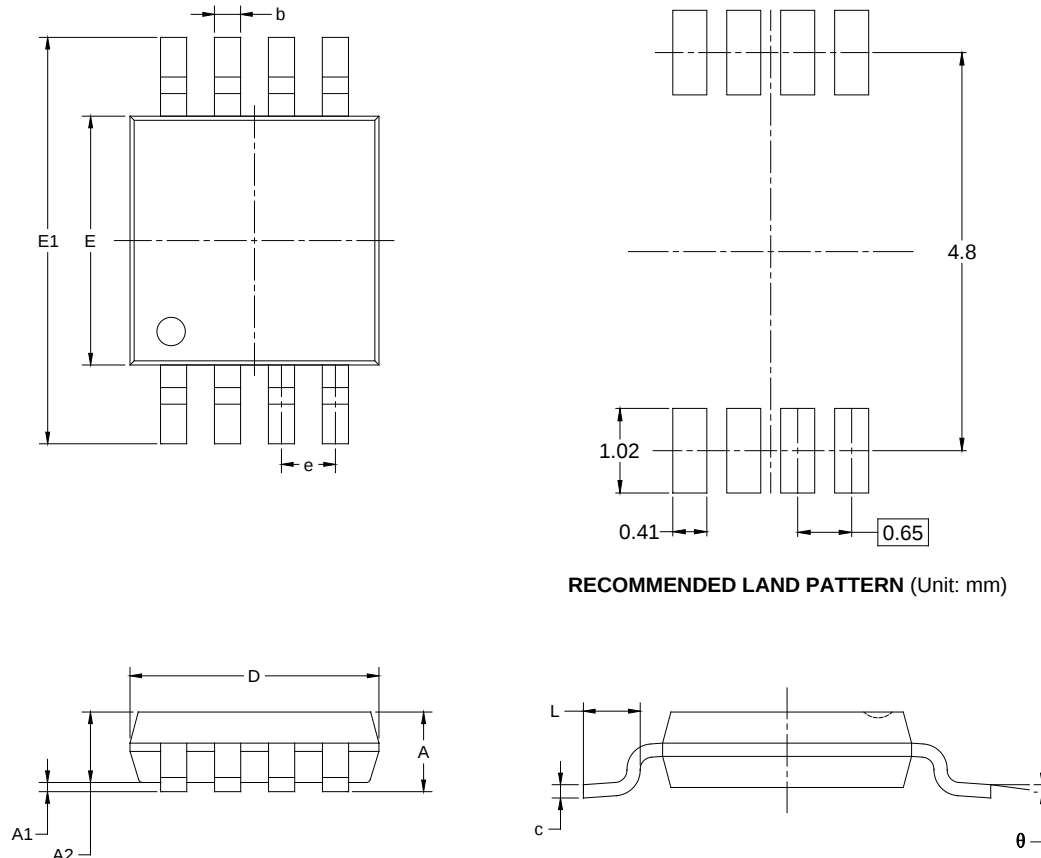
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.27 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

NOTES:

1. Body dimensions do not include mold flash or protrusion.
2. This drawing is subject to change without notice.

PACKAGE OUTLINE DIMENSIONS

MSOP-8



RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D	2.900	3.100	0.114	0.122
E	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
e	0.650 BSC		0.026 BSC	
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

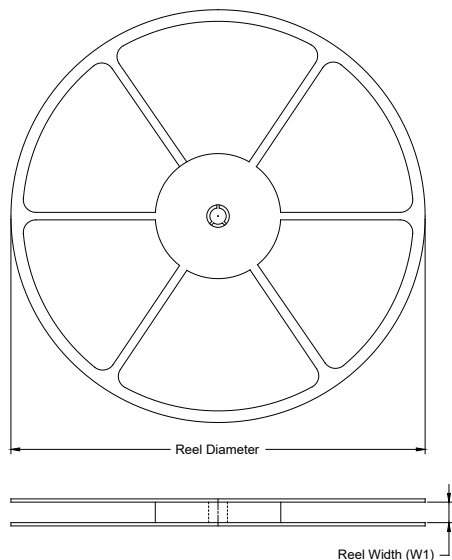
NOTES:

1. Body dimensions do not include mold flash or protrusion.
2. This drawing is subject to change without notice.

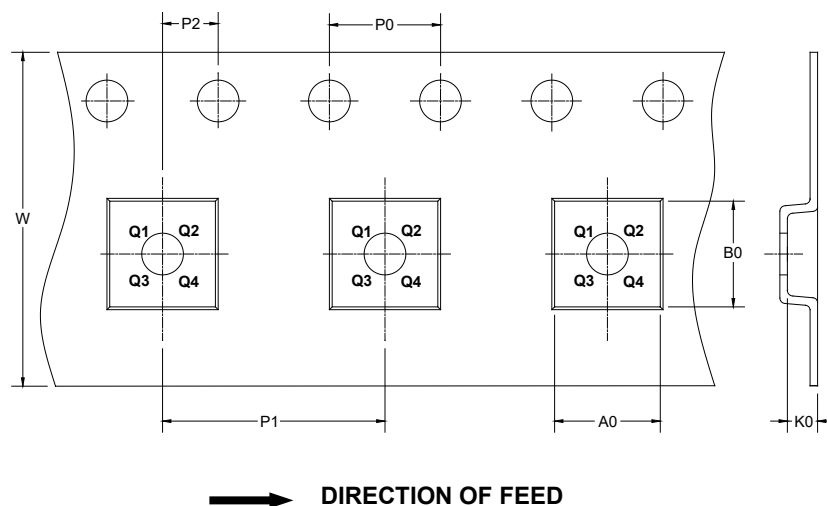
PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
WLCSP-1.57×1.57-8B	7"	9.2	1.73	1.73	0.72	4.0	4.0	2.0	8.0	Q1
TDFN-2×2-8AL	7"	9.5	2.30	2.30	1.10	4.0	4.0	2.0	8.0	Q1
TDFN-3×3-8BL	13"	12.4	3.35	3.35	1.13	4.0	8.0	2.0	12.0	Q1
SOIC-8	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1
MSOP-8	13"	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1

DD0001

PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18
13"	386	280	370	5

DD0002